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# Thermally Enhanced Co-Tunneling of Single Electrons in a Si Quantum Dot at 4.2 K

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Transport properties of a Si quantum dot at 4.2 K have been studied. A quantum dot is realized in the inversion layer of a Si-MOSFET with a dual-gate structure by introducing controllable tunnel barriers in the narrow channel. Periodic current oscillations due to the single-electron charging effect have been observed. With increasing tunnel barrier heights, Coulomb gaps appear in the I-V characteristics. Leakage current in the Coulomb blockade regime is quantitatively described in terms of the inelastic co-tunneling theory at finite temperatures.

#### 1. Introduction

Novel circuits and memories based on the Coulomb blockade of single-electron tunneling have recently been proposed and experimentally demonstrated. [1] However, in such single-electron devices, the process of simultaneous tunneling of different electrons across the neighboring barriers, known as co-tunneling [2], gives rise to a leakage current when the voltage is below the Coulomb-blockade threshold voltage, seriously limiting device operation. This paper reports on co-tunneling phenomena at 4.2 K in a single quantum dot formed in the inversion layer of a Si-MOSFET. We have observed current oscillations resulting from the single-electron charging effect, and found that the leakage current in the Coulomb blockade regime varies linearly with bias voltage, which agrees well with the inelastic co-tunneling theory [2].

# 2. Results and Discussion

The dual-gate structure [3] used in this study is shown in Fig. 1. The source and drain (not shown) are n<sup>+</sup> regions on a p<sup>-</sup>Si substrate, placed 5  $\mu$ m apart. Both the lower and upper gates are fabricated by electron beam lithography and chemical dry etching. The lower gate, on 10-nm-thick SiO<sub>2</sub>, forms a narrow inversion channel at the SiO<sub>2</sub>-substrate interface and increases the electron density by applying a positive voltage. The negatively biased upper gate with two arms, insulated from the lower gate by 100-nm-thick  $SiO_2$ , introduces potential barriers below the arms and changes the one-dimensional channel into a quantum dot by means of the field effect.

Figure 2 shows typical  $I_D - V_{LG}$  characteristics at 4.2 K when a quantum dot is formed in the channel. Current oscillation due to the single-electron charging effect is clearly seen. Peak positions are plotted in the inset of Fig. 2. These plots form a straight line, which means that the oscillation is periodic against  $V_{LG}$ . Since the periodicity  $\Delta V_{LG}$  (= 13.8 mV) corresponds to the voltage



Fig. 1 Dual-gate structure and a quantum dot formed in the channel.

difference required to add a single electron in a dot, the capacitance  $C_G$  between the lower gate and the quantum dot can be expressed as

$$C_{c} = e/\Delta V_{LC} = 1.2 \times 10^{-17} \, \text{F}.$$

Assuming a 10-nm-thick gate oxide, the area of a dot is calculated to be  $3500 \text{ nm}^2$ , which indicates that the field effect can confine electrons in a smaller region than the geometrical area defined by the dual-gate structure. If we consider a flat disk of an area of  $3500 \text{ nm}^2$ , a self capacitance of a dot  $C_s$  is

$$C_s = 8 \varepsilon \varepsilon_o r = 0.9 \times 10^{-17} \text{ F}.$$

Therefore, the total capacitance of a dot  $C_p$  is

$$C_p = C_c + C_s = 2.1 \times 10^{-17} \, \text{F}.$$

Thus, the charging energy of a quantum dot  $E_c$  at  $V_{UG}$  = -4 V is

$$E_c = e^2 / 2C_o = 3.8 \text{ meV},$$

which is much larger than the thermal energy at 4.2 K (= 0.36 meV) and is consistent with the observations of Coulomb blockade phenomena at 4.2 K.

Figure 3 shows the  $I_p - V_p$  characteristics using  $V_{UG}$ as a parameter. A Coulomb gap appears with increases in  $V_{UG}$  (i.e., increases in the tunnel barrier height). The extrapolated Coulomb-blockade threshold voltage  $V_{ik}^{C}$ when  $V_{ug}$  = - 5.8 V is about 5 mV, as indicated by the straight line in Fig. 3. In what follows, the leakage current when  $V_D$  is below  $V_{th}^{C}$  is discussed from the viewpoint of co-tunneling. Inelastic co-tunneling [2] is known to be the simultaneous tunneling of different electrons across different barriers via virtual charged states in the quantum dot, as is shown in Fig. 4,. This is thought to be a dominant leakage mechanism when the charging energy is sufficiently larger than the thermal energy. It must be kept in mind that inelastic co-tunneling creates electron-hole excitations in the dot, as is obvious in Fig. 4. Elastic co-tunneling [1] is thought to be negligible in our case since the quantum dot is not small enough.

The inelastic co-tunneling current in a two-barrier system at low temperature is given by [2]

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$$I_{\rm CT} \approx (2\pi T)^2 V + e^2 V^3, \tag{1}$$



Fig. 2  $I_D$ - $V_{LG}$  characteristics : Current oscillation is due to the single-electron charging effect. Inset : Peak positions of the current. The straight line shows that the oscillation is periodic. The periodicity is 13.8 mV.



Fig. 3  $I_D - V_D$  characteristics : Coulomb gap becomes visible as  $V_{UG}$  becomes more negative. The Coulomb-blockade threshold voltage  $V_{th}^C$  is about 5 mV when  $V_{UG}$  = -5.8 V.



Fig. 4 Mechanism of inelastic co-tunneling.

where V and T are drain voltage and temperature, respectively. To study the experimental data in terms of Eq.(1), a logarithmic plot of Fig. 3 for  $V_p \ge 0.3 \text{ mV}$  is shown in Fig. 5. When a quantum dot is formed (i.e.,  $V_{UG}$  = - 5.8 V), the data obtained at low voltages lie on a straight line with a slope equal to 1, as is expected from Eq. (1). With increases in  $V_p$ , the slope becomes larger than 1 over a particular voltage range, then returns to 1. This linear current at higher voltage agrees well with the classical "orthodox theory" [1] of Coulomb blockade. For quantitative discussion, the  $I_D$  -  $V_D$  characteristics for 0.3 mV  $< V_p < 3$  mV (= 0.6  $V_{th}^{c}$ ) are fitted by Eq. (1) in Fig. 6. The experimental data are fitted well by Eq. (1) giving T = 6.9 K. The higher effective temperature extracted from the experiment is thought to be due to the electron-hole excitations created during inelastic cotunneling in the quantum dot, as shown in Fig. 4.

### 3. Conclusion

In conclusion, we have shown a current oscillation at 4.2 K caused by the single-electron charging effect in a quantum dot formed in the inversion layer of a Si-MOSFET with a dual-gate structure. When the tunnel barrier height is increased, Coulomb gaps become visible. Moreover, when the bias voltage is far below the Coulomb-blockade threshold voltage, the current changes linearly with bias voltage, which agrees well with the co-tunneling theory at finite temperatures. The higher temperature extracted from the experimental results is attributed to the electron-hole excitations induced during inelastic co-tunneling.

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Fig. 5  $\text{Log}(I_D) - \text{Log}(V_D)$  curves of Fig. 3 for  $V_D > 0.3 \text{ mV}$ . Linear dependence of  $I_D$  on  $V_D$  is seen at low voltages even when a quantum dot is formed (i.e.,  $V_{UG} = -5.8 \text{ V}$ ). Lines with a slope equal to 1 are drawn as guides.



Fig. 6 Fit of  $I_D$  - $V_D$  characteristics with Eq. (1). Closed circles denote the experimental results.

### References

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